

We claim:

1. A photosensitive resin composition comprising a polyamic acid resin, a photosensitive agent, a dispersible compound dispersible in the polyamic acid resin, and a solvent.

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2. The photosensitive resin composition according to claim 1, wherein the dispersible compound is at least one compound selected from the group consisting of a polyacrylate oligomer, a polyether oligomer, a polyester oligomer, and a polyurethane oligomer.

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3. The photosensitive resin composition according to claim 1, wherein the amount of the photosensitive agent is 0.05 to 0.5 mol per mol of the polyamic acid resin.

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4. The photosensitive resin composition according to claim 1, wherein the amount of dispersible compound is 10 to 200 parts by weight per 100 parts by weight of the polyamic acid resin.

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5. A porous resin obtained by a process comprising the steps of:

removing the solvent from the photosensitive resin composition according to claim 1, to form a state that the dispersible compound is dispersed in the polyamic acid resin;

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removing the dispersible compound, to make the  
photosensitive resin composition porous; and  
curing the photosensitive resin composition.

5           6.    The porous resin according to claim 5, wherein the  
process further comprises the step of patterning the  
photosensitive resin composition by exposure and development.

          7.    The porous resin according to claim 5, which is used  
10 as an insulating layer of a circuit board.

          8.    The porous resin according to claim 5, which is used  
as an insulating layer of a wireless suspension board.

15           9.    A circuit board comprising an insulating layer  
comprising the porous resin according to claim 5.

          10.   The circuit board according to claim 9, which is a  
wireless suspension board.

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